

Product/Process Change Notification

N° 2021-023-A

Dear customer,

please find attached our Infineon Technologies AG PCN:

Introduction of an additional wafer production and additional wafer test location Infineon Technologies(Kulim) Sdn. Bhd, Kulim, Malaysia for several products in B4CD technology

Important information for your attention:

- Please respond to this PCN by indicating your decision on the approval form, sign it and return to your sales partner before 2021-12-29.
- Infineon aligns with the widely-recognized JEDEC STANDARD “JESD46”, which stipulates: “Lack of acknowledgement of the PCN within 30 days constitutes acceptance of the change.”
Notwithstanding the aforesaid individual agreements shall prevail.

Your prompt reply will help Infineon to assure a smooth and well-executed transition. If Infineon does not hear from your side by the due date, we will assume your full acceptance to this proposed change and its implementation.

Your attention and response to this matter is greatly appreciated.



On 16 April 2020, Infineon acquired Cypress.

We are now in the process of merging and consolidating our tools and processes for PCN, Information Notes, Errata and Product Discontinuance.

For further details, please visit our website:

<https://www.infineon.com/cms/en/about-infineon/company/cypress-acquisition/>

Infineon Technologies AG

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Chairman of the Supervisory Board: Dr. Wolfgang Eder

Management Board: Dr. Reinhard Ploss (CEO), Dr. Helmut Gassel, Jochen Hanebeck, Constanze Hufenbecher, Dr. Sven Schneider

Registered Office: Neubiberg

Commercial Register: München HRB 126492

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Products affected

Please refer to attached affected product list 1_cip21023_A

Detailed change information

Subject: Introduction of an additional wafer production and additional wafer test location Infineon Technologies(Kulim) Sdn. Bhd, Kulim, Malaysia for several products in B4CD technology

Reason/Motivation: Expansion of wafer production and wafer test to assure continuity of supply and enable flexible manufacturing.
MSL have been changed for product TLF4277-2LD to harmonize TSON platform dry pack requirements

Description	Old	New
PROCESS - WAFER PRODUCTION: Move all or parts of production to a different wafer fab site.	Infineon Technologies Austria AG, Villach, Austria	Infineon Technologies Austria AG, Villach, Austria AND Infineon Technologies (Kulim) Sdn. Bhd., Kulim, Malaysia
PACKING/SHIPPING: Dry pack requirements change	For TLF4277-2LD only: MSL 3	For TLF4277-2LD only: MSL 2a
TEST FLOW: Move of all or part of electrical wafer test and/or final test to a different test site.	Infineon Technologies Austria AG, Villach, Austria	Infineon Technologies Austria AG, Villach, Austria AND Infineon Technologies (Kulim) Sdn. Bhd., Kulim, Malaysia

Product identification

Wafer lot numbers from Villach start with VExxxxxx.
Wafer lot numbers from Kulim with 1Exxxxxx.
Traceability assured via date code.
No change in SP ordering number.

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Anticipated impact of change

Based on the qualification performed, Infineon does not expect any negative impact on quality, function and reliability. No change in form, fit and function expected.

DeQuMa-ID(s): SEM-PW-13 / SEM-PS-02 / SEM-TF-01

Attachments

1_cip21023_A	affected product list
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Time schedule

Final qualification report	available
First samples available	on request
Intended start of delivery [1]	2022-05-17
Last order date (LOD) [2]	2022-05-17
Last delivery date (LDD) [3]	2023-05-17

[1] provided date or earlier after customer approval

[2] Last time buy volume to be placed latest until LOD

[3] Delivery of new product can be earlier (see Intended start of delivery) and depends on approval

If you have any questions, please do not hesitate to contact your local sales office.



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Sales name	SP number	OPN	Package
TLE7257LE	SP000966908	TLE7257LEXUMA1	PG-TSON-8-1
TLE7268LC	SP001614988	TLE7268LCXUMA1	PG-TSON-14-3
TLE8457ALE	SP001423978	TLE8457ALEXUMA1	PG-TSON-8-1
TLF4277-2LD	SP001488242	TLF42772LDXUMA1	PG-TSON-10-2